



NOTES:

1. MATERIAL:

- 1.1 HOUSING: LCP.,UL94V-0
- 1.2 CONTACT: COPPER ALLOY
- 1.3 FITTING NAIL: COPPER ALLOY

2. FINISH:

- 2.1 CONTACT:
 - 1:GOLD FLASH PLATING ON CONTACT AND SOLDER AREA.
 - 50~100u" NICKEL UNDERPLATING OVERALL.
- 2.2 FITTING NAIL:
 - N:100~200u" TIN PLATING ON SOLDER TAILS.
 - 50~100u" NICKEL UNDERPLATING OVERALL.

3. REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.

4. SPEC. PLS. REFER TO PS-50280-XXXXX

5. PACKAGE PLS. REFER TO 88231-XXXXX-TRP

6. PART NUMBER

P/N LEGEND

51214-XXX X X-XXX

NO OF CKT

COLOR

001:BLACK

PACKING

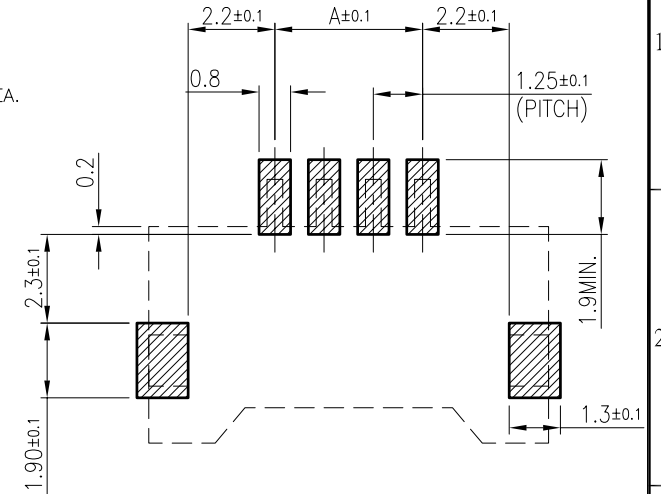
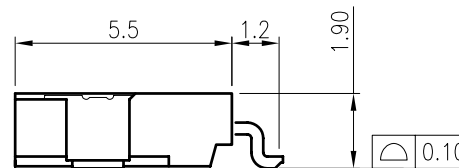
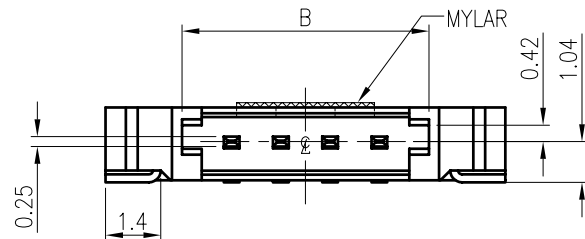
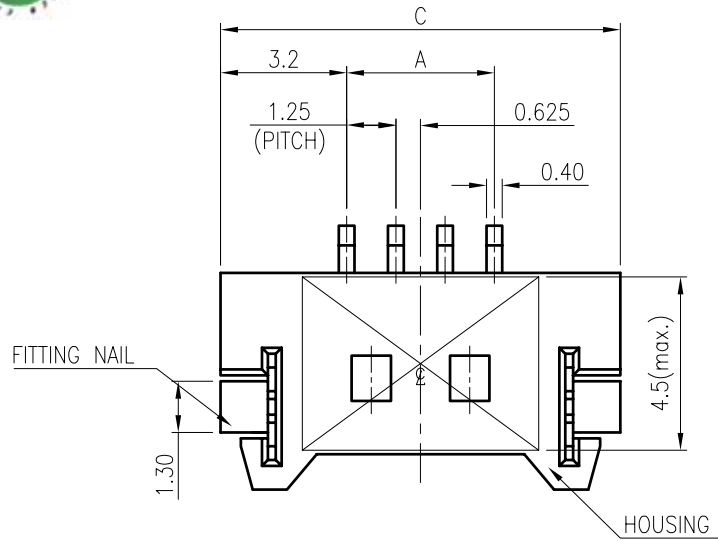
PLATING

0:TAPE&REEL WITHOUT MYLAR

1:G/F (LEAD FREE)

4:TAPE&REEL WITH MYLAR

N:MATT TIN(LEAD FREE)



RECOMMENDED P.C. BOARD PATTERN DIM. (REF.)

CKT.	DIM A	DIM B	DIM C	DIM D
10	11.25	13.77	17.65	10

一般公差 TOOLERANCES X ±0.5 .XX ±0.15 X ±0.25 .XXX ±0.1 ANGLES ±2°		宏致電子股份有限公司 Aces Electronics Co.,Ltd.		
檢驗尺寸標示 SYMBOLS INDICATE CLASSIFICATION DIMENSION MARK IS CRITICAL DIM. MARK IS MAJOR DIM.	品名 (TITLE) 1.25mm WIRE TO BOARD WAFER LPF-2 SMT R/A TYPE	製圖 (DR) 13/03/08 FENGXIAO 審核 (CHKD) CARL	圖號 (DWG NO.) 51214-XXXXX-XXX 核准 (APPD) JASON	
表面處理 (FINISH)	比例 (SCALE) 5:1	單位 (UNITS) mm		張數 (SHEET) 1 OF 1 尺寸 (SIZE) A4 版次 (REV) C